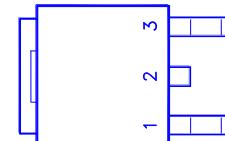
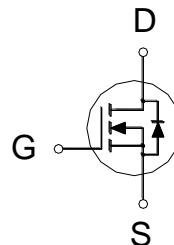


NIKO-SEM
**N-Channel Enhancement Mode
Field Effect Transistor**
P2206BD
TO-252
Halogen-Free & Lead-Free
PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D
60V	22.5mΩ	32A

**ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ Unless Otherwise Noted)**

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS		UNITS
Drain-Source Voltage		V_{DS}	60		V
Gate-Source Voltage		V_{GS}	± 20		V
Continuous Drain Current	$T_C = 25^\circ\text{C}$	I_D	32		A
	$T_C = 100^\circ\text{C}$		20		
Pulsed Drain Current ¹		I_{DM}	100		
Avalanche Current		I_{AS}	26		
Avalanche Energy	$L = 0.1\text{mH}$	E_{AS}	33.8		mJ
Power Dissipation	$T_C = 25^\circ\text{C}$	P_D	50		W
	$T_C = 100^\circ\text{C}$		20		
Junction & Storage Temperature Range		T_J, T_{stg}	-55 to 150		°C

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Case	$R_{\theta JC}$		2.5	°C / W
Junction-to-Ambient	$R_{\theta JA}$		62.5	

¹Pulse width limited by maximum junction temperature.
ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{V}, I_D = 250\mu\text{A}$	60			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	1.3	1.75	2.3	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0\text{V}, V_{GS} = \pm 20\text{V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 48\text{V}, V_{GS} = 0\text{V}$			1	μA
		$V_{DS} = 40\text{V}, V_{GS} = 0\text{V}, T_J = 125^\circ\text{C}$			10	
Drain-Source On-State Resistance ₁	$R_{DS(ON)}$	$V_{GS} = 4.5\text{V}, I_D = 12\text{A}$		19	30	$\text{m}\Omega$
		$V_{GS} = 10\text{V}, I_D = 20\text{A}$		17	22.5	

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Forward Transconductance ¹	g_{fs}	$V_{DS} = 5V, I_D = 20A$		40		S
DYNAMIC						
Input Capacitance	C_{iss}	$V_{GS} = 0V, V_{DS} = 25V, f = 1MHz$	812	1016	1219	pF
Output Capacitance	C_{oss}		100	125	150	
Reverse Transfer Capacitance	C_{rss}		48	81	113	
Gate Resistance	R_g	$V_{GS} = 0V, V_{DS} = 0V, f = 1MHz$	0.5	1	1.5	Ω
Total Gate Charge ²	$Q_{g(VGS=10V)}$	$V_{DS} = 30V, I_D = 20A$	18	23.2	28	nC
	$Q_{g(VGS=4.5V)}$		10.4	13	15.6	
Gate-Source Charge ²	Q_{gs}		2.6	3.2	3.8	
Gate-Drain Charge ²	Q_{gd}		4.4	7.4	10.4	
Turn-On Delay Time ²	$t_{d(on)}$	$V_{DS} = 30V$ $I_D \approx 20A, V_{GS} = 10V, R_{GEN} = 6\Omega$		38		nS
Rise Time ²	t_r			24		
Turn-Off Delay Time ²	$t_{d(off)}$			102		
Fall Time ²	t_f			35		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ($T_J = 25^\circ C$)						
Continuous Current ³	I_S				32	A
Forward Voltage ¹	V_{SD}	$I_F = 20A, V_{GS} = 0V$			1.3	V
Reverse Recovery Time	t_{rr}	$I_F = 20A, dI_F/dt = 100A / \mu S$	11	22	33	nS
Reverse Recovery Charge	Q_{rr}		7.5	15	22.5	nC

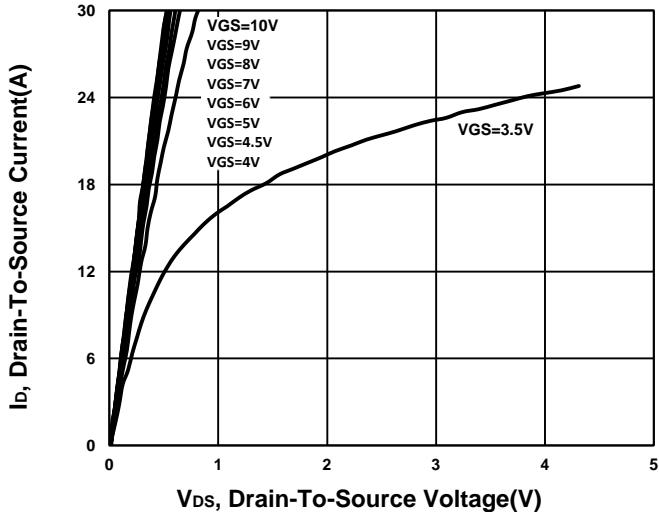
¹Pulse test : Pulse Width $\leq 300 \mu sec$, Duty Cycle $\leq 2\%$.²Independent of operating temperature.

NIKO-SEM

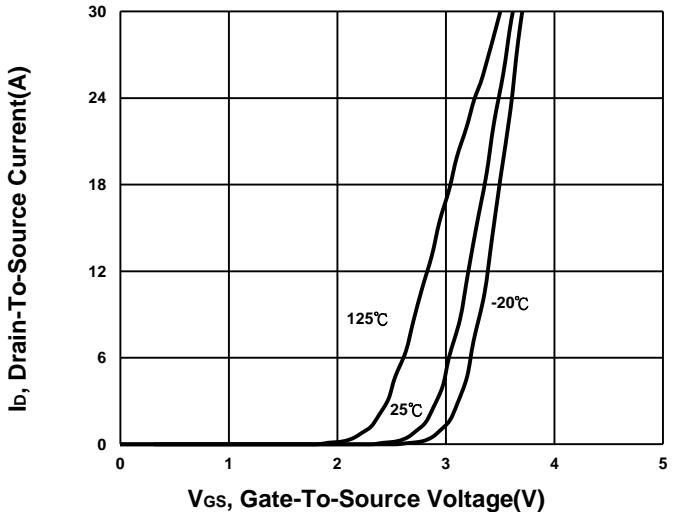
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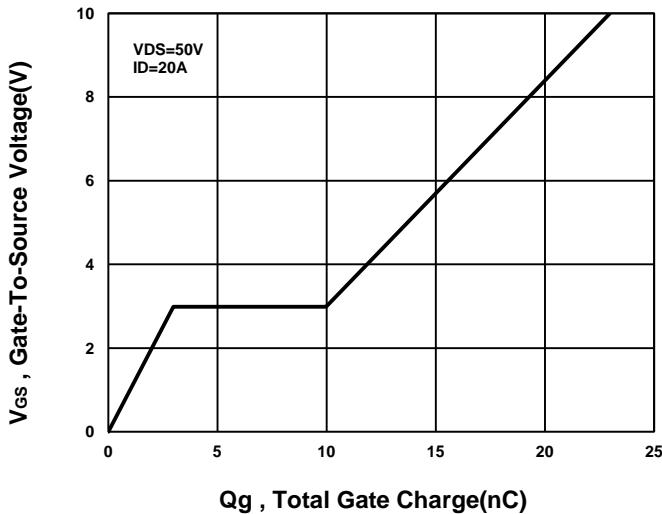
Output Characteristics



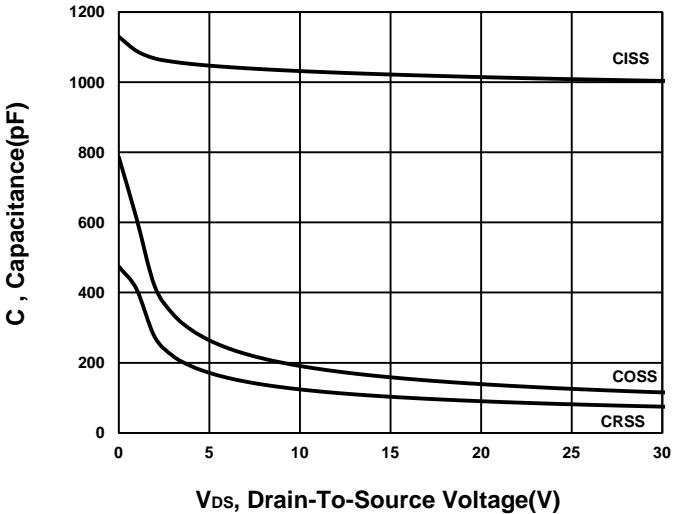
Transfer Characteristics



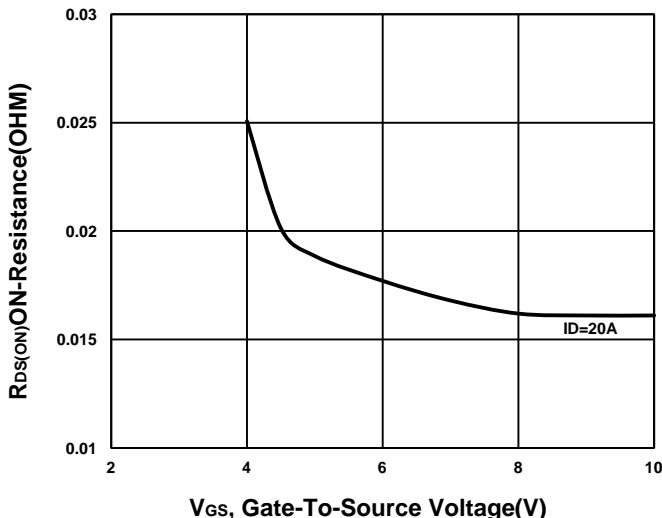
Gate charge Characteristics



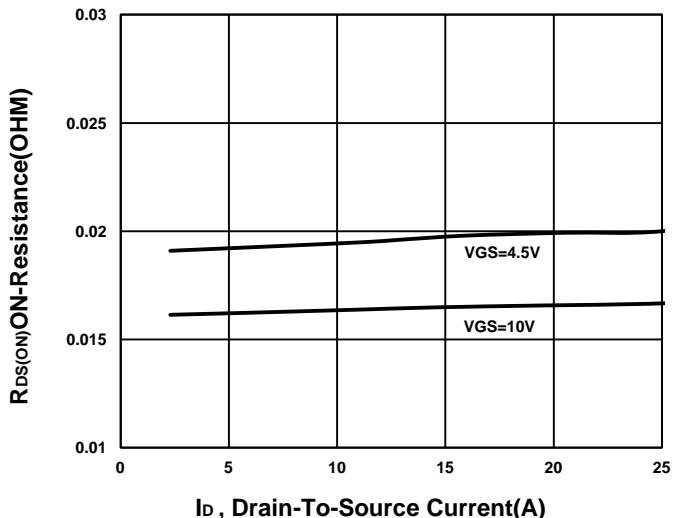
Capacitance Characteristic

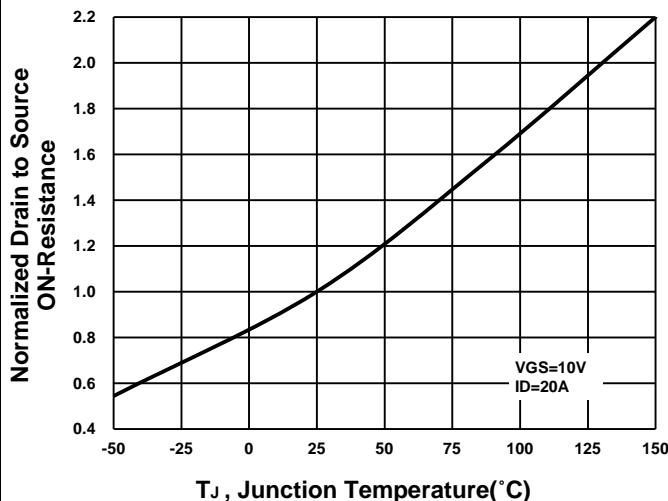
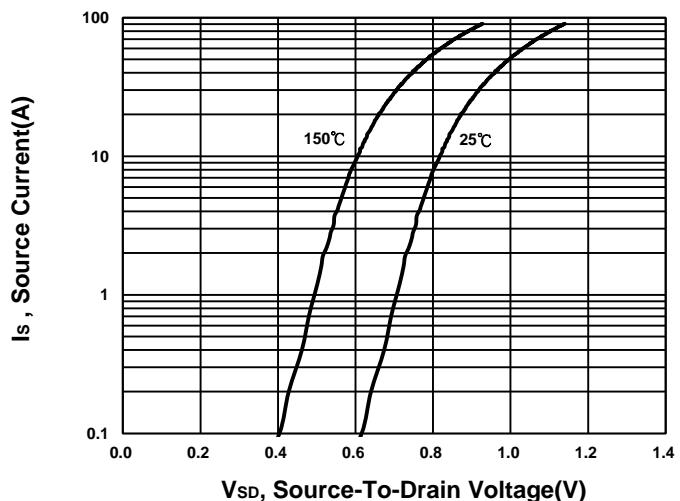
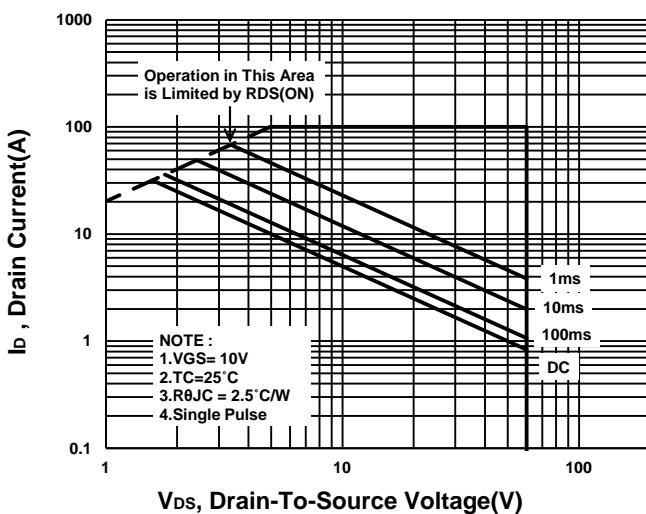
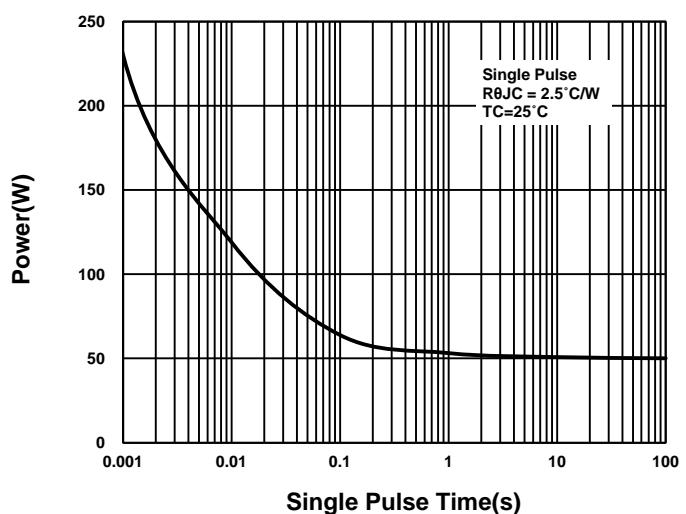


On-Resistance VS Gate-To-Source



On-Resistance VS Drain Current



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On-Resistance VS Temperature**Source-Drain Diode Forward Voltage****Safe Operating Area****Single Pulse Maximum Power Dissipation****Transient Thermal Response Curve**